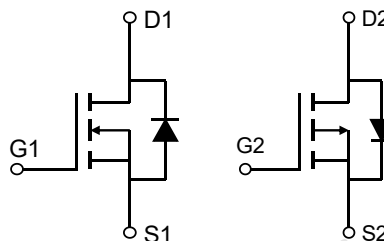


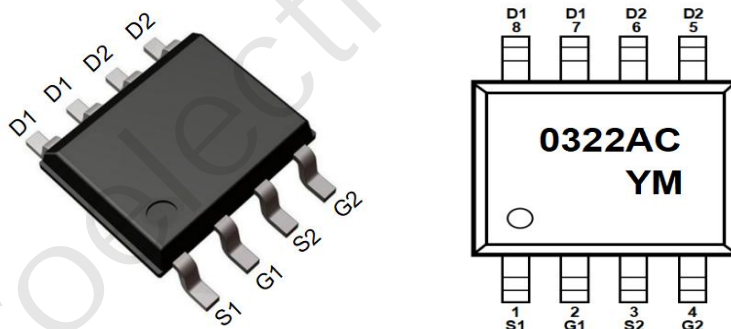
Description

Features

- 30V, 8A
 $R_{DS(ON)}$ Typ = 15.3m Ω @ V_{GS} = 10V
 $R_{DS(ON)}$ Typ = 22.5m Ω @ V_{GS} = 4.5V
- -30V, -5.1A
 $R_{DS(ON)}$ Typ = 34m Ω @ V_{GS} = -10V
 $R_{DS(ON)}$ Typ = 46m Ω @ V_{GS} = -4.5V
- Advanced Trench Technology
- Excellent $R_{DS(ON)}$ and Low Gate Charge
- Lead Free
- 100% UIS TESTED!
- 100% ΔV_d s TESTED!



Schematic Diagram



Marking and Pin Assignment

Application

- Load Switch
- PWM Application
- Power Management

Package Marking and Ordering Information

Device	Marking	Package	Outline	Reel Size	Reel (pcs)	Per Carton (pcs)
CRMPTL0322AC	0322AC	SOP-8	TAPING	13"	4000	40000

Absolute Maximum Ratings (@ T_J = 25°C unless otherwise specified)

Symbol	Parameter	N Value	P Value	Units
V_{DS}	Drain-to-Source Voltage	30	-30	V
V_{GS}	Gate-to-Source Voltage	± 20	± 20	V
I_D	Continuous Drain Current	$T_A = 25^\circ\text{C}$	8	A
		$T_A = 100^\circ\text{C}$	5	A
I_{DM}	Pulsed Drain Current ⁽¹⁾	32	-20.4	A
E_{AS}	Single Pulsed Avalanche Energy ⁽²⁾	12	12	mJ
P_D	Power Dissipation	$T_A = 25^\circ\text{C}$	2	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient ⁽³⁾	62.5	62.5	°C/W
T_J, T_{STG}	Junction & Storage Temperature Range	-55 to 150		°C

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
Off Characteristics						
V _{(BR)DSS}	Drain-Source Breakdown Voltage	I _D = 250μA, V _{GS} = 0V	30	-	-	V
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 30V, V _{GS} = 0V	-	-	1.0	μA
I _{GSS}	Gate-Body Leakage Current	V _{DS} = 0V, V _{GS} = ±20V	-	-	±100	nA
On Characteristics						
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} , I _D = 250μA	1	1.5	2	V
R _{DS(ON)}	Static Drain-Source ON-Resistance ⁽⁴⁾	V _{GS} = 10V, I _D = 3A	-	15.3	20	mΩ
		V _{GS} = 4.5V, I _D = 2A	-	22.5	29.5	mΩ
Dynamic Characteristics						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz	-	510	-	pF
C _{oss}	Output Capacitance		-	61	-	pF
C _{rss}	Reverse Transfer Capacitance		-	51	-	pF
Q _g	Total Gate Charge	V _{GS} = 0 to 10V V _{DS} = 15V, I _D = 3A	-	10	-	nC
Q _{gs}	Gate Source Charge		-	2	-	nC
Q _{gd}	Gate Drain("Miller") Charge		-	2	-	nC
Switching Characteristics						
t _{d(on)}	Turn-On DelayTime	V _{GS} = 10V, V _{DD} = 15V I _D = 3A, R _{GEN} = 3Ω	-	4	-	ns
t _r	Turn-On Rise Time		-	6	-	ns
t _{d(off)}	Turn-Off DelayTime		-	12	-	ns
t _f	Turn-Off Fall Time		-	3	-	ns
Drain-Source Diode Characteristics and Max Ratings						
I _S	Maximum Continuous Drain to Source Diode Forward Current		-	-	8	A
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	32	A
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0V, I _S = 3A	-	-	1.2	V
trr	Body Diode Reverse Recovery Time	I _F = 3A, di/dt = 100A/us	-	8	-	ns
Qrr	Body Diode Reverse Recovery Charge		-	2	-	nC

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}$, $V_{GS} = 0\text{V}$	-30	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -30\text{V}$, $V_{GS} = 0\text{V}$	-	-	-1.0	μA
I_{GSS}	Gate-Body Leakage Current	$V_{DS} = 0\text{V}$, $V_{GS} = \pm 20\text{V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}$, $I_D = -250\mu\text{A}$	-1	-1.6	-2.5	V
$R_{DS(ON)}$	Static Drain-Source ON-Resistance ⁽⁴⁾	$V_{GS} = -10\text{V}$, $I_D = -3\text{A}$	-	34	45	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}$, $I_D = -2\text{A}$	-	46	60	$\text{m}\Omega$

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{GS} = 0\text{V}$, $V_{DS} = -15\text{V}$, $f = 1\text{MHz}$	-	491	-	pF
C_{oss}	Output Capacitance		-	67	-	pF
C_{rss}	Reverse Transfer Capacitance		-	53	-	pF
Q_g	Total Gate Charge	$V_{GS} = 0$ to -10V $V_{DS} = -15\text{V}$, $I_D = -2\text{A}$	-	11	-	nC
Q_{gs}	Gate Source Charge		-	2	-	nC
Q_{gd}	Gate Drain("Miller") Charge		-	2	-	nC

Switching Characteristics

$t_{d(on)}$	Turn-On DelayTime	$V_{GS} = -10\text{V}$, $V_{DD} = -15\text{V}$ $I_D = -2\text{A}$, $R_{GEN} = 3\Omega$	-	3	-	ns
t_r	Turn-On Rise Time		-	2	-	ns
$t_{d(off)}$	Turn-Off DelayTime		-	25	-	ns
t_f	Turn-Off Fall Time		-	15	-	ns

Drain-Source Diode Characteristics and Max Ratings

I_S	Maximum Continuous Drain to Source Diode Forward Current	$V_{GS} = 0\text{V}$, $I_S = -3\text{A}$	-	-	-5.1	A
I_{SM}	Maximum Pulsed Drain to Source Diode Forward Current		-	-	-20.4	A
V_{SD}	Drain to Source Diode Forward Voltage		-	-	-1.2	V
t_{rr}	Body Diode Reverse Recovery Time		-	9	-	ns
Q_{rr}	Body Diode Reverse Recovery Charge		-	3	-	nC

Notes:

1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.
2. E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = 15\text{V}$, $V_G = 10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = 7\text{A}$
 E_{AS} condition: Starting $T_J = 25^\circ\text{C}$, $V_{DD} = -15\text{V}$, $V_G = -10\text{V}$, $R_G = 25\Omega$, $L = 0.5\text{mH}$, $I_{AS} = -7\text{A}$
3. $R_{\theta JA}$ is measured with the device mounted on a 1inch^2 pad of 2oz copper FR4 PCB
4. Pulse Test: Pulse Width $\leq 300\mu\text{s}$, Duty Cycle $\leq 0.5\%$.

Test Circuit

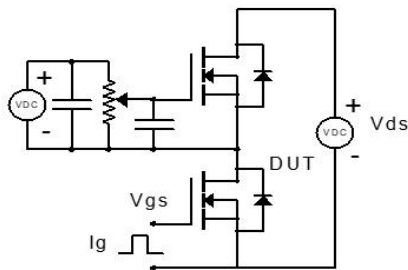


Figure 1: Gate Charge Test Circuit & Waveform

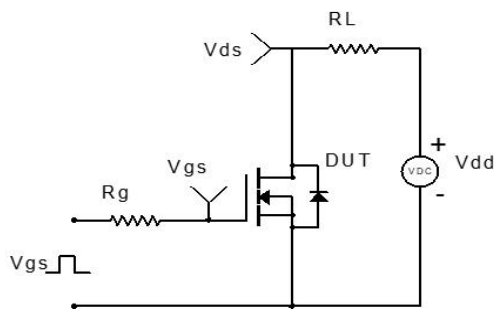


Figure 2: Resistive Switching Test Circuit & Waveform

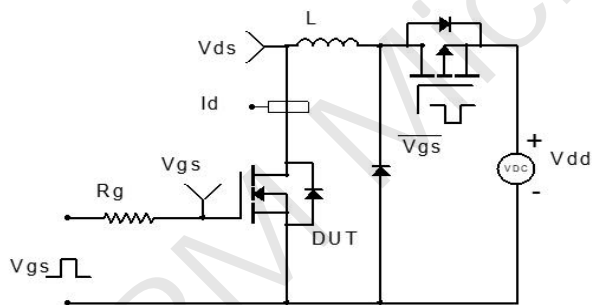


Figure 3: Unclamped Inductive Switching Test Circuit & Waveform

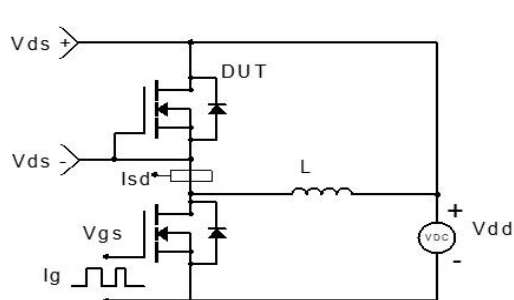
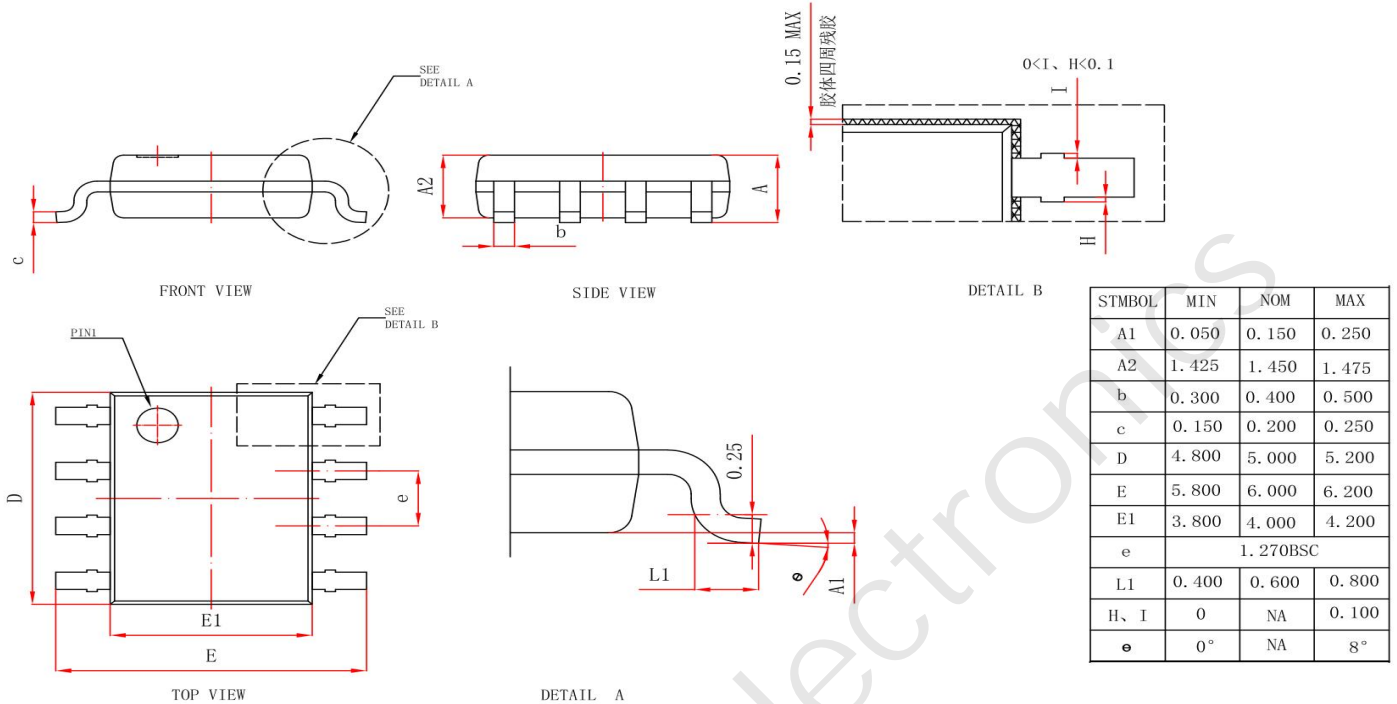


Figure 4: Diode Recovery Test Circuit & Waveform

Package Mechanical Data(SOP-8)




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